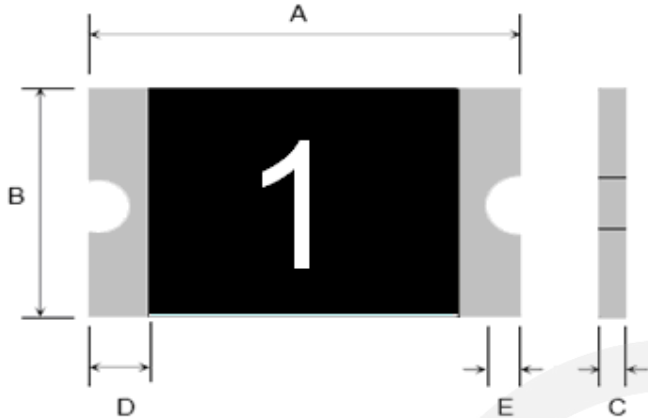


**PPTC DEVICE**


Terminal pad materials :Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification  
RS 186-9E and ANSI/J-STD-002 Category 3.

Marking : Part identification 1=005

Table1 :DIMENTION(Unit : mm)

Model	Marking	A		B		C		D	
		Min.	Max.	Min.	Max.	Min.	Max	Min.	Min.
JK-SMD0805-005-30	1	2.00	2.20	1.20	1.50	0.45	0.80	0.20	0.10

Table2 :PERFORMANCE RATINGS:

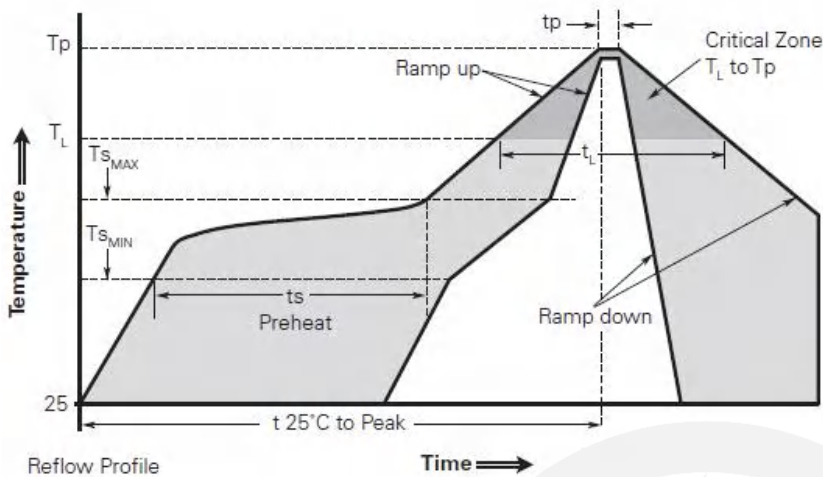
Model	Marking	$V_{max}$ (Vdc)	$I_{max}$ (A)	$I_{hold}$ @25°C (A)	$I_{trip}$ @25°C (A)	$P_d$ Typ (W)	Maximum Time To Trip		Resistance		
							Current (A)	Time (Sec)	$R_{i_{min}}$ (Ω)	$R_{i_{typ}}$ (Ω)	$R_{i_{max}}$ (Ω)
JK-SMD0805-005-30	1	30.0	100	0.05	0.20	0.50	0.5	1.50	1.5	3.0	30.000

Table3:Test Conditons and Standards

Item	Test Conditon	Standard
Initial Resistance	25°C	1.50~20.0Ω
$I_H$	25°C, 0.05A, 60min	No Trip
$T_{trip}$	25°C, 0.5A	≤1.5s
Trip endurance	30V, 100A, 60min	No arcing or burning

**Operating Temperature: -40°C TO 85°C**

**Packaging: Bulk ,5000pcs per bag**

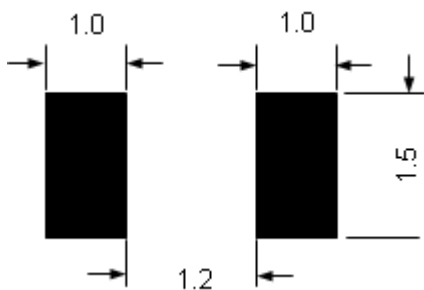
**Solder reflow conditions**


Profile Feature	Pb-Free Assembly
<b>Average ramp up rate (<math>T_{S_{MAX}}</math> to <math>T_p</math>)</b>	3°C/second max.
<b>Preheat</b>	
• Temperature min. ( $T_{S_{MIN}}$ )	150°C
• Temperature max. ( $T_{S_{MAX}}$ )	200°C
• Time ( $t_{S_{MIN}}$ to $t_{S_{MAX}}$ )	60-120 seconds
<b>Time maintained above:</b>	
• Temperature ( $T_L$ )	217°C
• Time ( $t_L$ )	60-150 seconds
<b>Peak/Classification temperature (<math>T_p</math>)</b>	260°C
<b>Time within 5°C of actual peak temperature</b>	
Time ( $t_p$ )	30 seconds max.
<b>Ramp down rate</b>	3°C/second max.
<b>Time 25°C to peak temperature</b>	8 minutes max.

**Note:** All temperatures refer to topside of the package, measured on the package body surface.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHs leadfree process.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

**Recommended pad layout (mm)**


**WARNING**

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage ( $L di/dt$ ) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

